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(12) **United States Design Patent** (10) **Patent No.:** **US D933,618 S**
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(54) **SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**

USPC D10/80, 103; D13/110, 133, 139, 154, D13/173, 182; D14/217, 432, 433
CPC H01L 20/4238; H01L 23/528; H01L 29/0696; H01L 29/1095; H01L 29/417; H01L 29/66068; H01L 29/1608; H01L 29/7395; H01L 29/7802; H01L 29/66325; H01L 29/66348; H01L 29/161; H01L 29/162; H01L 29/163; H01L 29/164; H01L 29/165; H01L 29/166; H01L 29/167; H01L 21/18; H01L 21/19; H01L 21/20; H01L 21/21; H01L 21/22; H01L 21/23; H01L 21/24; H01L 21/25; H01L 21/26; H01L 21/27; H01L 21/28; H01L 21/29; H01L 21/30

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front view of a semiconductor module showing our new design;

FIG. 2 is a rear view of the semiconductor module thereof;

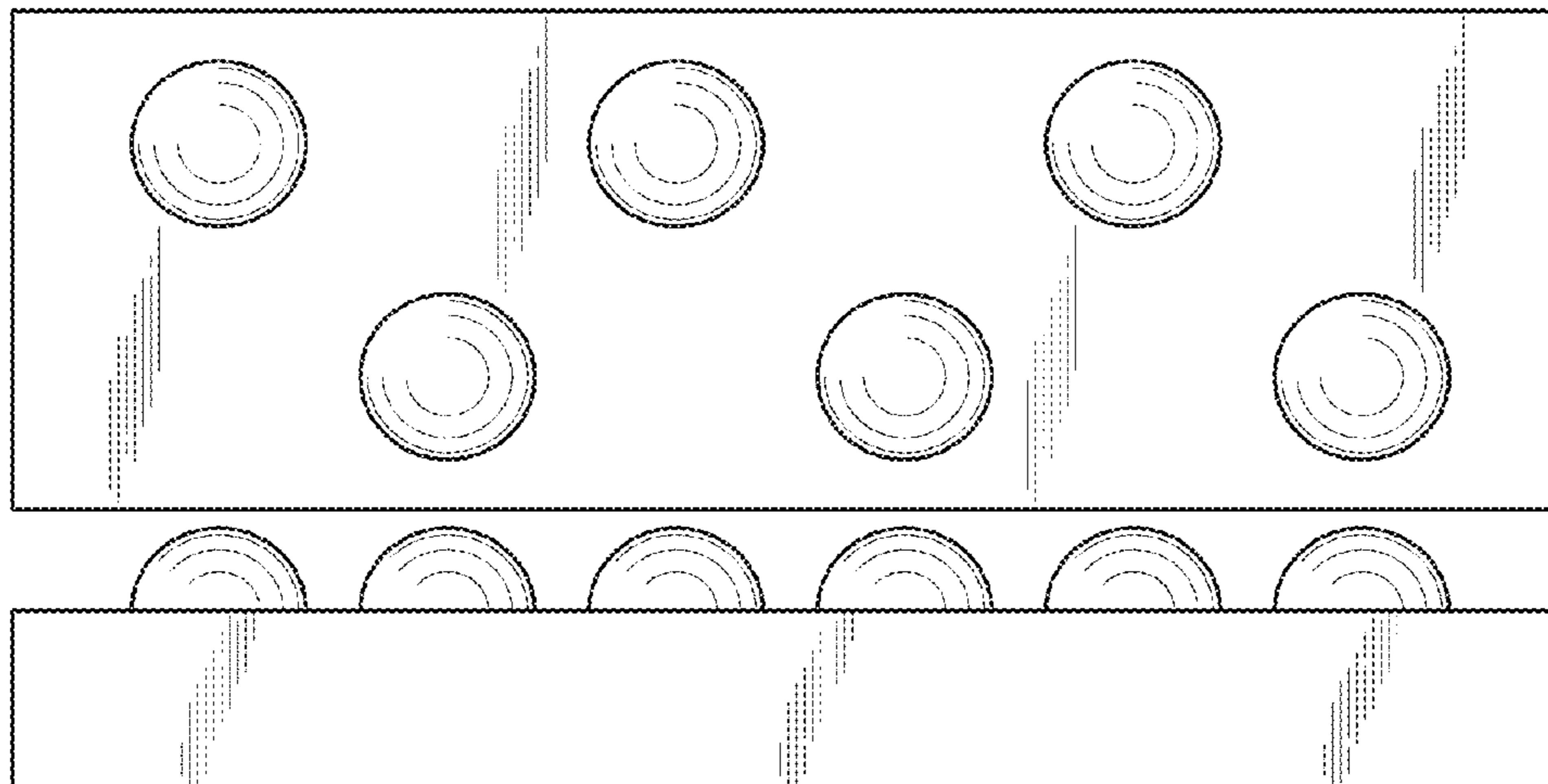
FIG. 3 is a left view of the semiconductor module thereof;

FIG. 4 is a right view of the semiconductor module thereof;

FIG. 5 is a top side view of the semiconductor module thereof; and,

FIG. 6 is a bottom side view of the semiconductor module thereof.

(Continued)



The thinner lines other than a thicker line in the front view, the rear view, the left side view the right side view, the top view, and the bottom view represents a shape of a three-dimensional shape.

1 Claim, 6 Drawing Sheets

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FIG. 1

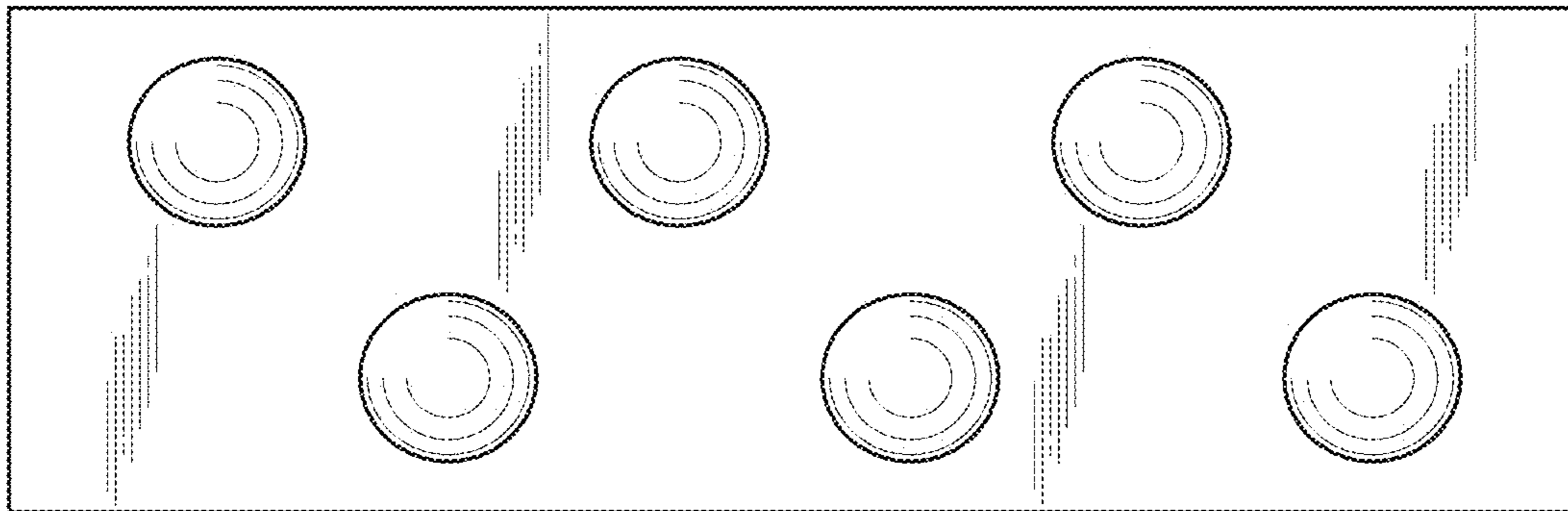


FIG.2

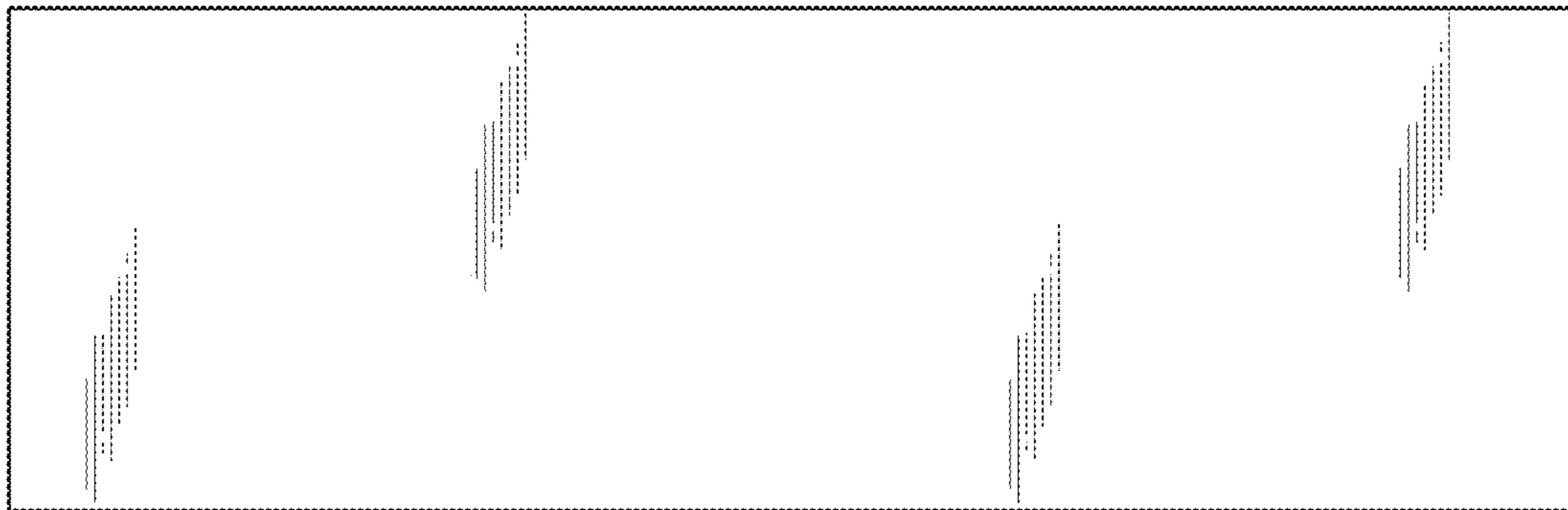


FIG.3

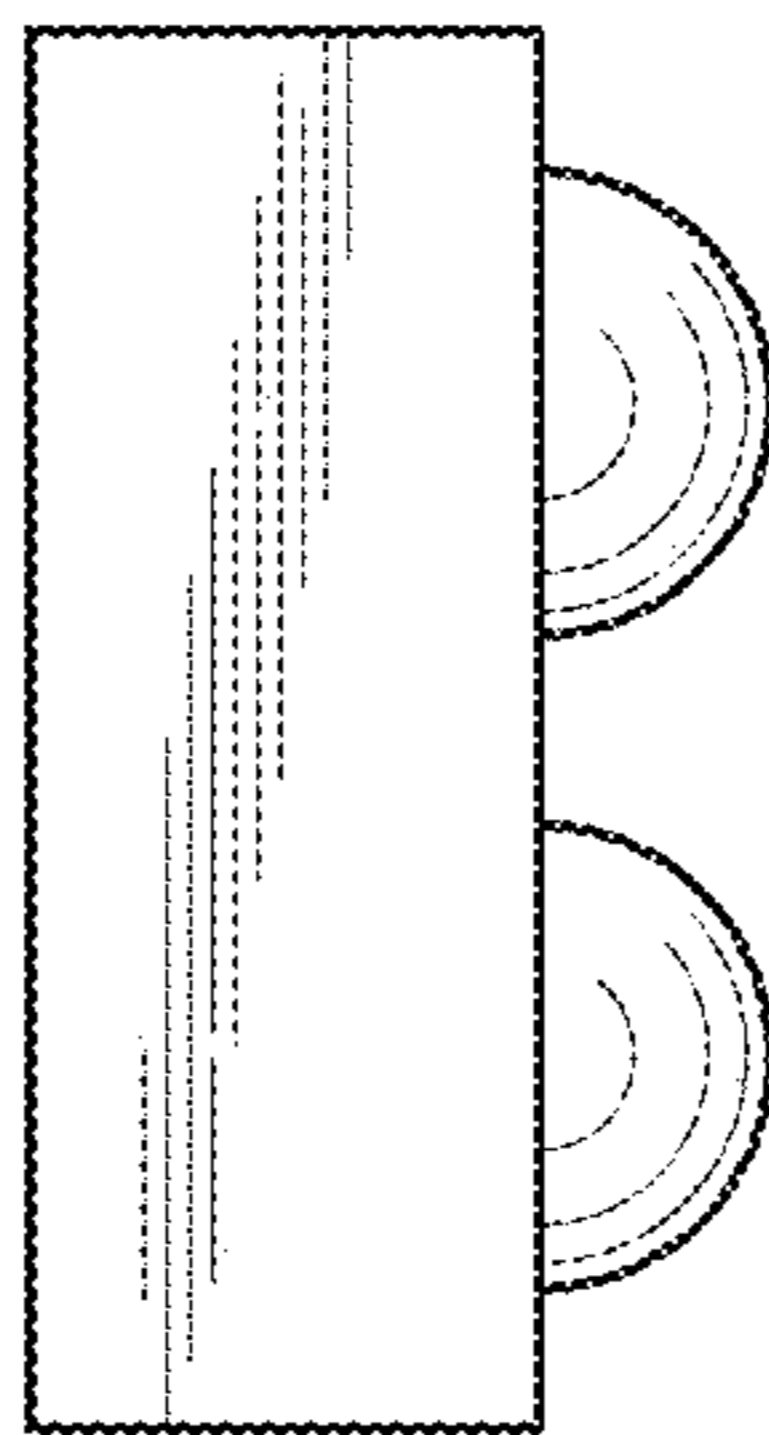


FIG.4

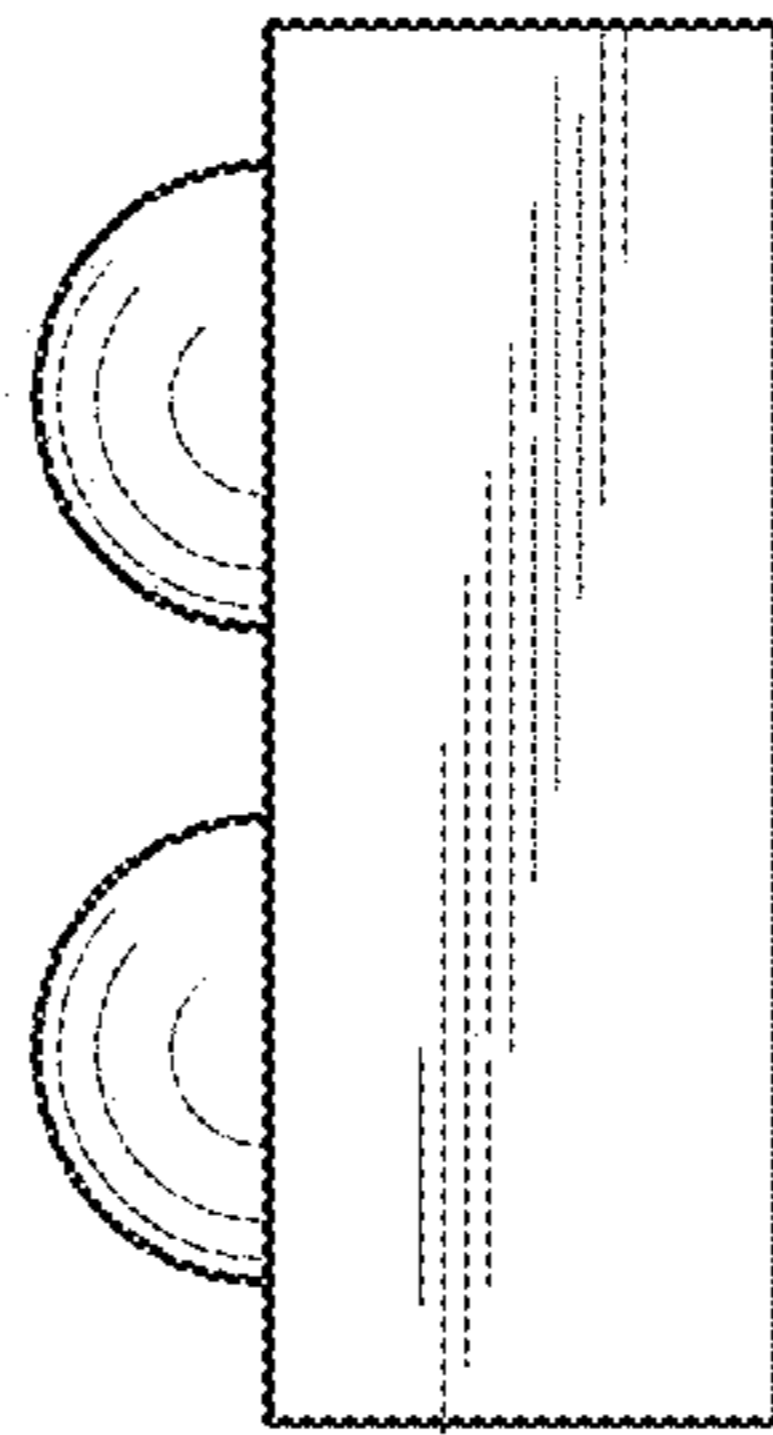


FIG.5

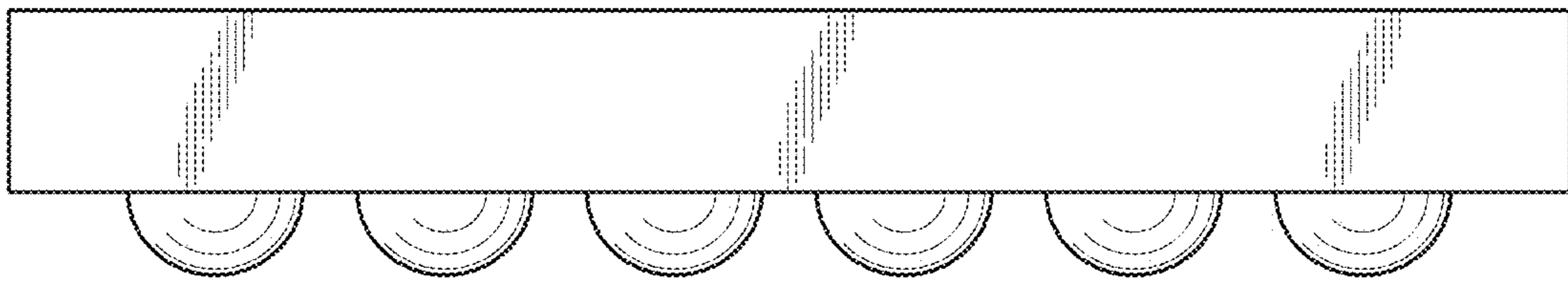


FIG.6

